



Equipment List, Electrical

Applicable for Z530c and Z530i

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1 General

This document describes the equipment needed, in addition to the equipment listed in the Mechanical Equipment List, to upgrade the applicable product(s)'s software, functional test and to repair the product(s) at an Electrical Repair Level. The first section is equipment that can be purchased from a Sony Ericsson Parts and Tools warehouse. The second section is equipment that must be purchased from other vendors.

2 Column Definitions

2.1 Description Columns

- Pos = (Position Number) = The equipment reference numbers used in the Installation Instruction documents.
- Description = The name of the equipment.
- Part Number = The Sony Ericsson part number to use when ordering from a Sony Ericsson Parts and Tools warehouse.
- Comments = Additional information that helps to specify or clarify the equipment.




2.2 Process Columns

These columns show which processes use the equipment. An "X" in a column indicates that the equipment must be used, and a "Z" in a column indicates that the use of that equipment is optional.

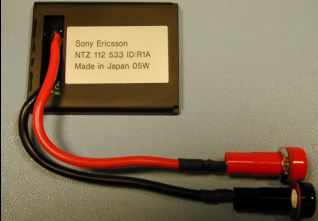
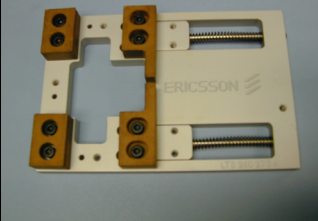
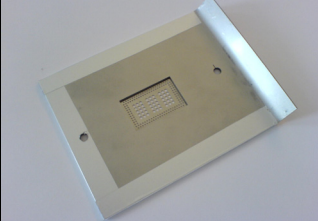

- Test = A manual and/or automated method of evaluating the functionality of a phone.
- Repair = A method of fixing a phone.


3 Repair Equipment, Electrical

3.1 Sony Ericsson-Provided Repair Equipment

Pos	Description	Part Number	Comments	Picture	Test	Repair
9	Sony Ericsson Programming Interface (SEPI)	LTN 214 1484	The Sony Ericsson Programming Interface (SEPI) is used in conjunction with the SEPI interface cable (POS 10), the USB computer cable (POS 43) and battery charger (POS 27) to perform calibration on this product.			X
10	Sony Ericsson Programming Interface (SEPI) cable	KRY 101 1119	A battery charger (POS 27) needs to be connected to this cable during calibration.			X
51	RF Cable	RPM 119 855			X	X




Pos	Description	Part Number	Comments	Picture	Test	Repair
52	Battery Eliminator	NTZ 112 533	If using the Battery Eliminator to power the handset during the GNG Test or Calibration routine you must use a high quality DC source. (See POS-77 for Power Supply requirements.)		Z	Z
54	Rework Fixture for PCB	LTD 260 273	Used to hold the PCB during repair.			X
	MTT Soldering Paste Application Fixture	LTM 901 743	To be used when replacing the RF module. (N1200: Mini T-Top)			X
62	RF Probe Assembly	SXA 109 6356	To be connected to the RF cable (POS-51).		Z	X

Pos	Description	Part Number	Comments	Picture	Test	Repair
	RF Holder	NTZ 112 1068	Used together with antenna RF Probe connector and RF cable with phone model Z530.			



3.2 Equipment Provided by Other Supplier

Pos	Description	Comments	Picture	Test	Repair
27	Battery Charger (Standard SEMC charger applicable for Z530)	The battery charger needs to be connected to the Sony Ericsson Programming Interface Cable during calibration.			X
43	USB Computer Cable	Type A to Type B USB cable. This is part of the hardware needed for performing calibration. This cable connects the computer (POS 96) to the SEPI (POS 9).			X



Pos	Description	Comments	Picture	Test	Repair
76	<p>Test and Calibration Instrument (Chose one of the following.)</p> <p>Anritsu MT 8801B</p> <p>Required Components:</p> <ul style="list-style-type: none"> • MT8801B (Radio Com. Analyser) • MT8801B-02 (SG-local) • MX880115A (GSM Measurement Software) <p>Required Software:</p> <ul style="list-style-type: none"> • Main 4.02 • System 4.05 	<p>If it is preferred to use a test instrument for GNG that is not specified, the test script must be written according to 2/1524-2/FEA 209 544/103 and approval of the test script <u>must</u> be obtained from Sony Ericsson.</p>		X	X
	<p>Anritsu MT 8801C</p> <p>Required Components:</p> <ul style="list-style-type: none"> • MT8801C (Radio Com. Analyser) • MX880115A (GSM Measurement Software) <p>Required Software:</p> <ul style="list-style-type: none"> • Main 4.02 • System 4.05 			X	X



Pos	Description	Comments	Picture	Test	Repair
	Anritsu MT 8802A Required Components: <ul style="list-style-type: none">• MT8802A (Radio Com. Analyser)• MX880215A (GSM Measurement Software) Required Software: <ul style="list-style-type: none">• Main 1.11• System 2.07			X	X
	Agilent 8960 Required Components: <ul style="list-style-type: none">• E5515C (8960 Series 10 Mainframe)• Option E5515C-002 (2nd RF source) Required Software <ul style="list-style-type: none">• E1968A GSM Test Application.			X	X



Pos	Description	Comments	Picture	Test	Repair
	Willtek 4403/4405/4407 Required Components: <ul style="list-style-type: none">Firmware 4.21 or greaterThe 4403 instrument needs to have option # M897163 installed.			X	X
	Willtek 4202 Required Components: <ul style="list-style-type: none">M101302 - 4202S Mainframe	This instrument is only capable of running a stand alone Go/No Go test. (SERP not required.) Note: This instrument does not support the calibration routine.		X	



Pos	Description	Comments	Picture	Test	Repair
77	Power Supply (w/digital readout) NOTE! If using the Power Supply in conjunction with the Battery Eliminator (Dummy Battery) to power the phone during the GNG test or Calibration routine a high quality DC source that meets the following requirements <u>must</u> be used.	Device Requirements: <ul style="list-style-type: none"> • Output Voltage: 0-5 volt minimum. • Output Current: 0-2 amps minimum. • Transient response time: < 100 μs Some examples of Power Supplies that meet these requirements are as follows: <ul style="list-style-type: none"> • Agilent 66xx series • Agilent 663x series 		Z	Z
78	Small Convection (Hot Air) Device	Device Requirements: <ul style="list-style-type: none"> • The device should allow variable adjustment over a temperature range. • The device should be capable of reaching an upper temperature of 426.7°C (800°F) or more. The range of airflow the device is capable of generating should fall under 20 litre/minute.			X

Pos	Description	Comments	Picture	Test	Repair
79	Large Convection (Hot Air) Device	<p>Certain components on the parts list can only be replaced using this device. These parts are specified in the parts list.</p> <ul style="list-style-type: none"> The device should allow variable temperature adjustment and be capable of reaching an upper temperature of 426.7°C (800°F) or more. The range of airflow the device is capable of generating should be above 20 litre/minute. 			X
80	Nozzles for Large Convection (Hot Air) Device	NOTE: Only necessary if you have a large convection device.			X
81	Digital Multi-meter	Used for troubleshooting failures			Z
82	Microscope	Minimum magnification required is 10x			X
83	GPIB Card	<p>National Instruments or Keithley</p> <p>NOTES:</p> <ul style="list-style-type: none"> Drivers are required and should be supplied with a card. A GPIB card is not required if testing is being performed using the Willtek 420x instrument. 		Z	X



Pos	Description	Comments	Picture	Test	Repair
84	GPIB Cable	This cable is only required if a GPIB card is used.		Z	X
88	Power cable – Red <i>NOTE: Only necessary if using the Battery Eliminator (Dummy Battery).</i>	Cable Requirements: <ul style="list-style-type: none"> • Minimum cross sectional area of conductor = 1.2mm² • Maximum length = 1.5 m • One end of cable must have a male banana-type connector to be able to interface with the battery eliminator. • The other end of the cable needs whatever connection is necessary to connect to the power supply that you have. 		Z	Z
89	Power cable – Black <i>NOTE: Only necessary if using the Battery Eliminator (Dummy Battery).</i>	Cable Requirements: <ul style="list-style-type: none"> • Minimum cross sectional area of conductor = 1.2mm² • Maximum length = 1.5 m • One end of cable must have a male banana-type connector to be able to interface with the battery eliminator. • The other end of the cable needs whatever connection is necessary to connect to the power supply that you have. 		Z	Z



Pos	Description	Comments	Picture	Test	Repair
90	Component baking oven	<p>Temperature requirements: 125°C +5°C/-0°C</p> <p>Required for drying moisture sensitive components.</p> <p>Below are links to several companies that sell convection ovens.</p> <p>http://www.cascadetek.com/forcedlist.php</p> <p>http://www.wisoven.com/lab1.htm</p> <p>http://www.shellab.com/products.html</p> <p>http://www.terrauniversal.com/products/ovens/imperiaivmechcon.php</p> <p>http://www.labsynergy.com/products_laboratoryovens.asp?keyword=*laboratoryovens</p>			X




Pos	Description	Comments	Picture	Test	Repair
91	RF Shield Package Rohde & Schwarz RF Shield Package <ul style="list-style-type: none"> CMU-Z10 – Shield box CMU-Z11 – Antenna Coupler 	Using an RF shield package is one of the options for testing the applicable product(s). Testing of the applicable product(s) can also be preformed by using the combination of an RF Probe (POS 62), Holder RF Connector (POS-63) and an RF cable (POS 51). NOTE: The Rohde & Schwarz package will require the use of a precision N-type male to SMA female RF adapter to mate with the SEMC RF cable (see POS 110 for adapter ordering information).		Z	
	Flux	Lead-free solder does not require a special flux. The “No Clean” flux used with leaded products is acceptable. Although some manufacturers are developing fluxes specially made for use with lead-free solder (higher evaporation temperatures, less smoke, etc.), these are not required.			X
	Low Static Heat Protection Tape	This tape is required to protect adjacent components from hot air.			X



Pos	Description	Comments	Picture	Test	Repair
96	Computer	<p>One of the following operating systems must be used:</p> <ul style="list-style-type: none"> Windows 2000 with service pack 2 or higher Windows XP <p>Minimum Requirements:</p> <ul style="list-style-type: none"> One unused PCI slot for GPIB card 2 USB Ports The processor and RAM of the computer should at least meet the the minimum requirements specified by the operating system's manufacturer. 		Z	X
99	Test SIM	According to your Instrument supplier		X	
109	Printer	Optional, but recommended		Z	Z






Pos	Description	Comments	Picture	Test	Repair
110	<p>RF adapter for RF shield box</p> <ul style="list-style-type: none">The adapter for a Rohde & Schwarz Shield box must be a precision N-type male to SMA female adapter.	<p>This adapter is used to connect the RF shield box to the RF cable (POS 51) and is only required if a shield package is going to be used for testing.</p> <p>Recommended source:</p> <ul style="list-style-type: none">Pasternack Enterprises – (949) 261-1920 or www.pasternack.comPart number: PE9430		Z	







3.3 Lead-free Solder Equipment

The items in this table, and any other soldering tools or material that make physical contact with the solder, must remain lead-free. They must be adequately labelled to make their lead-free status clearly and easily recognized.

				Test	Repair
Pos	Description	Comments	Picture		
	<p>Lead-free Solder</p> <p>Note: The solder must be composed of Tin, Silver, and Copper, and nothing else. The exact composition ratio may vary, but it must be Tin, Silver, and Copper only. This composition may also be known as SnAgCu or SAC.</p>	<p>Manufacturers of LF Solder:</p> <ul style="list-style-type: none"> - Tamura (www.tamura-kaken.co.jp) Part # TLF-206-93F - Multicore (www.multicore.com) Part # 96SC - Senju (www.senju-m.co.jp) Part # M705 			X
	Lead-free Soldering paste	To be used when replacing the RF module.			X
	<p>Lead-free labels (sheet of 24)</p> <p>SEMC Part # SVF9301379 (These labels are available from the Sony Ericsson Parts and Tools Warehouse.)</p>	Required for labeling all soldering tools and materials that contact the solder.			X
	Soldering Tips				X



				Test	Repair
Pos	Description	Comments	Picture		
	<p>Soldering Iron</p> <p>If one work bench is divided to accommodate both leaded and lead-free solder, then each side of the bench should have its own iron.</p>	<ul style="list-style-type: none"> The device should allow variable temperature adjustment and be capable of reaching an upper temperature of 426.7°C (800°F) or more. 			X
	Wicking Tape				X
	Tip Tinner				X
	Tip Cleaner (steel wool)				X

4 Revision History

Rev.	Date	Changes / Comments
A	2006-03-23	Initial Release
B	2006-11-14	Equipment update